

3RD CALL FOR PAPERS

ABOUT EPTC

The 22nd Electronics Packaging Technology Conference (EPTC'2020) is an international event organized by the IEEE RS/EPS/EDS Singapore Chapter and co-sponsored by IEEE Electronics Packaging Society (EPS). EPTC'2020 will feature keynotes, technical sessions, short courses, forums. It aims to provide a good coverage of technology developments in all areas of electronics packaging. It is a major forum for the exchange of knowledge and provides opportunities to network and meet with leading international experts from all over the world since 1997. EPTC is the flagship conference of IEEE EPS in Region 10.

Our thoughts are with those who are affected by the COVID-19 outbreak. At this point, we are planning a physical conference. However, for those authors whose travel plans are genuinely disrupted by COVID-19, we will provide the opportunity to present your latest work remotely.

We are pleased to announce the following keynote speakers: (1) Ahmer Syed, Qualcomm, and (2) John Lau, Unimicron. A Panel Session on Panel-Level Packaging is also being planned (tentative panellists from Deca, ASE, Fraunhofer IZM, Intel).

CONFERENCE TOPICS

You are invited to submit abstract(s), presenting new developments in the following categories:

- ❑ **Advanced Packaging:** Advanced Flip-chip, 2.5D & 3D, embedded passives & actives on substrates, System in Packaging, Embedded chip packaging technologies, Panel level packaging, RF, Microwave & Millimeter-wave, Power and Rugged Electronics Packaging, etc.
- ❑ **TSV/Wafer Level Packaging:** Wafer level packaging, Embedded chip packaging, 2.5D/3D integration, Silicon & Glass interposer, CoWoS, FoCoS, InFo, eWLB, Bumping technologies, etc.
- ❑ **Interconnection Technologies:** Au/Ag/Cu/Al Wire-bond / Wedge bond technology, Flip-chip & Cu pillar, Solder alternatives, Cu to Cu, Wafer level bonding & die attachment (Pb-free), etc.
- ❑ **Emerging Technologies:** Packaging technologies for MEMS, biomedical, Optoelectronics, Internet of things, Photovoltaic, Printed electronics, Wearable electronics, Photonics, LED, etc.
- ❑ **Materials and Processing:** Advanced materials (such photoresist, polymer dielectrics, solder, die attach, underfill), Substrates, Lead-frames, PCB for advanced packaging, Assembly processes using advanced materials, etc.
- ❑ **Assembly and Manufacturing Technology:** Assembly equipment automation and improvements. Embedded/Hybrid Package Manufacturing Processes. Warpage Control and Management in Board Level Assembly, Thin Die/Package Handling and Assembly. Large/Ultra Large Package (SiP, SIM, MCP) Integration and Processing. Panel Level Manufacturing. Smart Manufacturing technology. Data analytics. Advanced metrology. Machine learning.
- ❑ **Advanced Materials and Process Manufacturing Technology:** Processing characterization of advanced materials, Substrates, Lead-frames, etc. Advanced equipment for assembly process and handling. Large/Ultra Large Package (SiP, SIM, MCP) Integration and Processing. Panel Level Manufacturing.

- ❑ **Electrical Simulation & Characterization:** Power plane modeling, Signal integrity analysis by simulations and characterization, 2D/2.5D/3D package level high-speed signal design, Characterization and test methodologies.
- ❑ **Mechanical Simulation & Characterization:** Thermal-mechanical interaction study, Moisture, Fracture, Fatigue, dynamic impact modeling and characterization. Process modeling, etc.
- ❑ **Thermal Characterization & Cooling Solutions:** Thermal characterization and simulation, Component, system and product level thermal management and characterization
- ❑ **Quality, Reliability & Failure Analysis:** Silicon, component, board and system level reliability assessment, Interfacial adhesion, Accelerated testing, Failure characterization, etc.
- ❑ **Special Sessions:** Please submit your proposals to the General Chair and Technical Chair.

IMPORTANT DATES

Online abstract submission start	1 May 2020
Closing of abstract submission	15 Jun 2020-30 June 2020
Notification of acceptance	1 Aug 2020

Please check on <http://www.eptc-ieee.net> for latest updates.

ABSTRACT AND PAPER SUBMISSION

Abstracts are solicited which describe original and unpublished work. The abstract should be at least 500-750 words long and clearly state the purpose, methodology, results (including data, drawings, graphs and photographs) and conclusions of the work. Authors can indicate preference of oral or poster presentation.

All submissions must be in English and should be made via the online submission system found at <http://www.eptc-ieee.net>. The required file format is Adobe Acrobat® PDF or MS Word in one single file for each submission. The abstracts must be received by 10th June 2020. Authors must include their affiliation, mailing address, telephone number and email address. Authors will be notified of paper acceptance and publication instructions by 1st August 2020. The final manuscript for publication in the conference proceedings is due on 10th September 2020. The conference proceeding is an official IEEE publication and the accepted papers that registered and presented (oral & poster) will be available in IEEE Xplore.

BEST PAPER AWARDS

Awards will be given to the best oral papers from Academia, Industry, Students, and to the best interactive paper. More details can be found at <http://www.eptc-ieee.net>

CALL FOR SHORT COURSES/PANEL SESSION

The conference program includes short courses and panel discussion which will be conducted by leading experts in the field. Details will be updated in the conference website. Proposals for short courses can be submitted to pdcc@eptc-ieee.net. Proposals for panel session can be submitted to generalchair@eptc-ieee.net.

CALL FOR EXHIBITION / SPONSORSHIP PARTICIPATION

A tabletop exhibition featuring suppliers of materials, equipment and services to the microelectronics packaging and manufacturing, will be held during the conference. For details, please email to exhibition@eptc-ieee.net and sponsorship@eptc-ieee.net.

EPTC 2020: website: <http://www.eptc-ieee.net> Email: secretariat@eptc-ieee.net Join us on: [Linkedin \[EPTC OC\]](#)



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